

GENERAL DESCRIPTION

Passivated high commutation triacs in a plastic full pack envelope intended for use in circuits where high static and dynamic dV/dt and high dl/dt can occur. These devices will commutate the full rated rms current at the maximum rated junction temperature without the aid of a snubber.

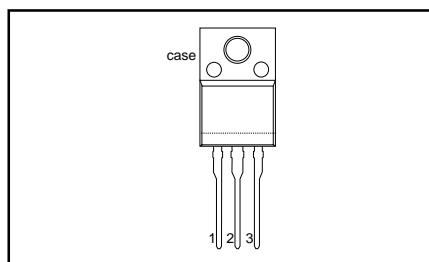
QUICK REFERENCE DATA

SYMBOL	PARAMETER	BTA204X-			MAX.	MAX.	MAX.	UNIT
		500B	600B	800B				
V_{DRM}	Repetitive peak off-state voltages	500C	600C	800C				V
$I_{T(RMS)}$	RMS on-state current	500	600	800				A
I_{TSM}	Non-repetitive peak on-state current	4	25	4	25			A

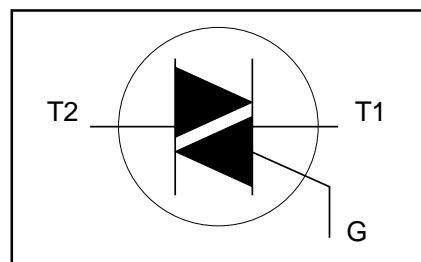
PINNING - TO220F

PIN	DESCRIPTION
1	main terminal 1
2	main terminal 2
3	gate
case	isolated

PIN CONFIGURATION



SYMBOL



LIMITING VALUES

Limiting values in accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.			UNIT
V_{DRM}	Repetitive peak off-state voltages		-	-500 500 ¹	-600 600 ¹	-800 800	V
$I_{T(RMS)}$	RMS on-state current	full sine wave; $T_{hs} \leq 92^\circ C$	-	4			A
I_{TSM}	Non-repetitive peak on-state current	full sine wave; $T_j = 25^\circ C$ prior to surge					
I^2t dl/dt	I^2t for fusing Repetitive rate of rise of on-state current after triggering	$t = 20$ ms $t = 16.7$ ms $t = 10$ ms $I_{TM} = 6$ A; $I_G = 0.2$ A; $dl_G/dt = 0.2$ A/ μ s	-	25	27	3.1	A
I_{GM} V_{GM} P_{GM} $P_{G(AV)}$	Peak gate current Peak gate voltage Peak gate power Average gate power	over any 20 ms period	-	2	5	5	A V W W
T_{stg} T_j	Storage temperature Operating junction temperature		-40	150	125		°C °C

¹ Although not recommended, off-state voltages up to 800V may be applied without damage, but the triac may switch to the on-state. The rate of rise of current should not exceed 6 A/ μ s.

ISOLATION LIMITING VALUE & CHARACTERISTIC

$T_{hs} = 25^\circ C$ unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V_{isol}	R.M.S. isolation voltage from all three terminals to external heatsink	$f = 50-60 \text{ Hz}$; sinusoidal waveform; R.H. $\leq 65\%$; clean and dustfree	-		2500	V
C_{isol}	Capacitance from T2 to external heatsink	$f = 1 \text{ MHz}$	-	10	-	pF

THERMAL RESISTANCES

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$R_{th j-hs}$	Thermal resistance junction to heatsink	full or half cycle with heatsink compound	-	-	5.5	K/W
$R_{th j-a}$	Thermal resistance junction to ambient	without heatsink compound in free air	-	55	7.2	K/W

STATIC CHARACTERISTICS

$T_j = 25^\circ C$ unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.		UNIT
I_{GT}	Gate trigger current ²	BTA204X- $V_D = 12 \text{ V}$; $I_T = 0.1 \text{ A}$ T2+ G+ T2+ G- T2- G-	-	-	50	35	mA
I_L	Latching current	$V_D = 12 \text{ V}$; $I_{GT} = 0.1 \text{ A}$ T2+ G+ T2+ G- T2- G-	-	-	50	35	mA
I_H	Holding current	$V_D = 12 \text{ V}$; $I_{GT} = 0.1 \text{ A}$ T2+ G+ T2+ G- T2- G-	-	-	30	20	mA
V_T V_{GT}	On-state voltage Gate trigger voltage	$I_T = 5 \text{ A}$ $V_D = 12 \text{ V}$; $I_T = 0.1 \text{ A}$ $V_D = 400 \text{ V}$; $I_T = 0.1 \text{ A}$ $T_j = 125^\circ C$	-	1.4 0.7 0.4	30	20	V
I_D	Off-state leakage current	$V_D = V_{DRM(max)}$; $T_j = 125^\circ C$	0.25	0.1	1.7 1.5 -	0.5	mA

DYNAMIC CHARACTERISTICS

$T_j = 25^\circ C$ unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	UNIT	
dV_D/dt	Critical rate of rise of off-state voltage	BTA204X- $V_{DM} = 67\% V_{DRM(max)}$; $T_j = 125^\circ C$; exponential waveform; gate open circuit	1000	1000	-	V/ μ s
dl_{com}/dt	Critical rate of change of commutating current	$V_{DM} = 400 \text{ V}$; $T_j = 125^\circ C$; $I_{T(RMS)} = 4 \text{ A}$; $dV_{com}/dt = 20 \text{ V}/\mu\text{s}$; gate open circuit	6	3	-	A/ms
t_{gt}	Gate controlled turn-on time	$I_{TM} = 12 \text{ A}$; $V_D = V_{DRM(max)}$; $I_G = 0.1 \text{ A}$; $dl_G/dt = 5 \text{ A}/\mu\text{s}$	-	-	2	μ s

² Device does not trigger in the T2-, G+ quadrant.

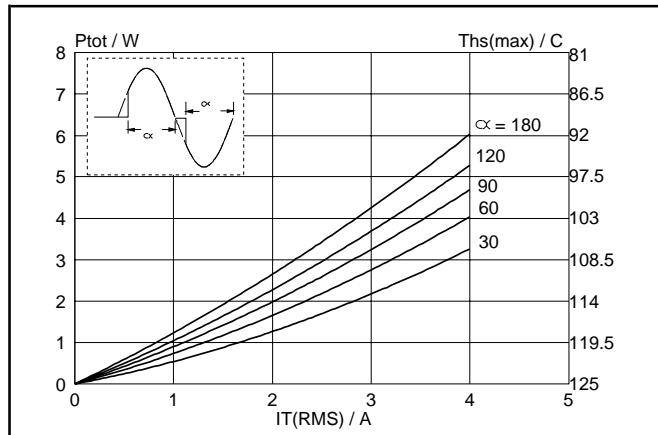


Fig.1. Maximum on-state dissipation, P_{tot} , versus rms on-state current, $I_{T(RMS)}$, where α = conduction angle.

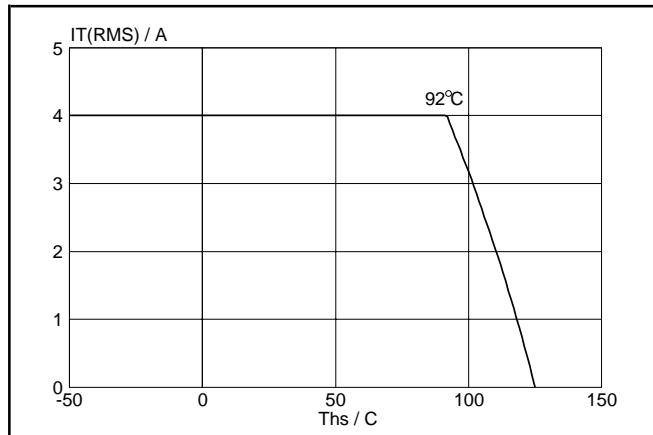


Fig.4. Maximum permissible rms current $I_{T(RMS)}$, versus heatsink temperature T_{hs} .

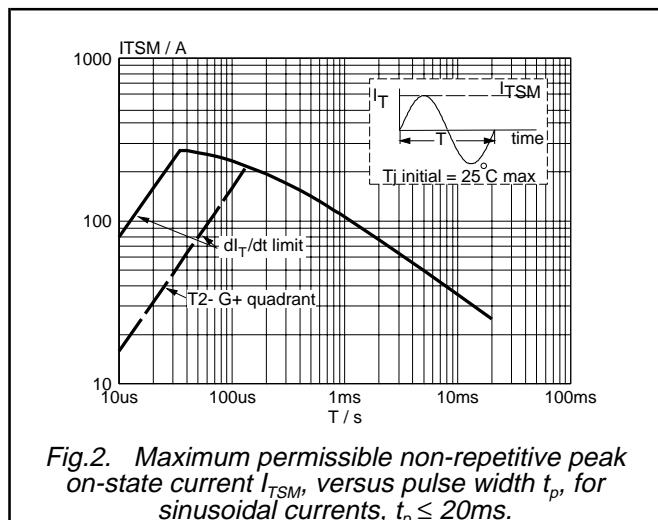


Fig.2. Maximum permissible non-repetitive peak on-state current I_{TSM} , versus pulse width t_p , for sinusoidal currents, $t_p \leq 20\text{ms}$.

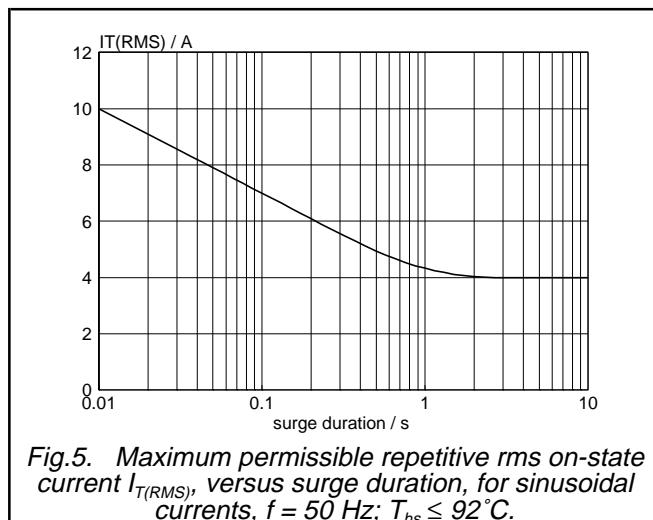


Fig.5. Maximum permissible repetitive rms on-state current $I_{T(RMS)}$, versus surge duration, for sinusoidal currents, $f = 50\text{ Hz}$; $T_{hs} \leq 92^\circ\text{C}$.

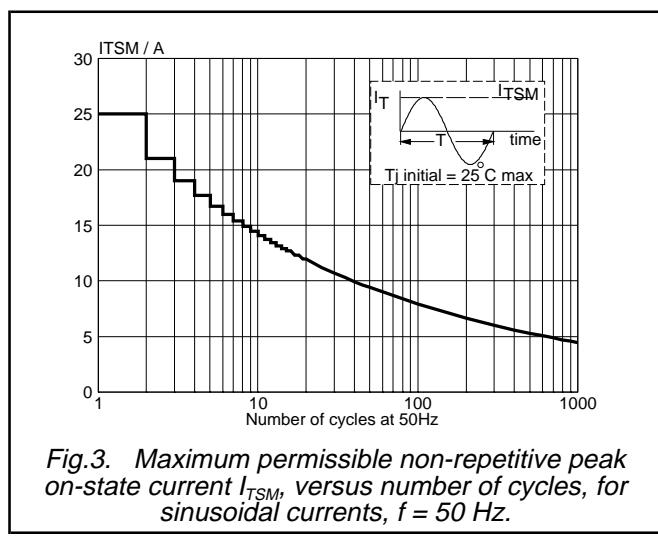


Fig.3. Maximum permissible non-repetitive peak on-state current I_{TSM} , versus number of cycles, for sinusoidal currents, $f = 50\text{ Hz}$.

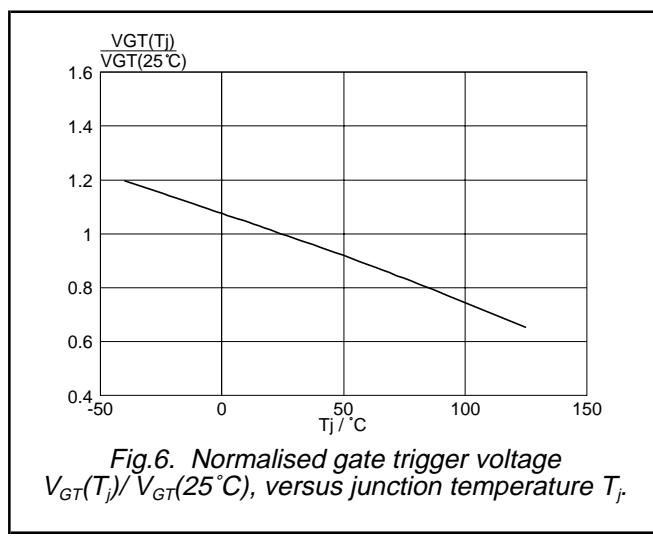


Fig.6. Normalised gate trigger voltage $V_{GT}(T_j)/V_{GT}(25^\circ\text{C})$, versus junction temperature T_j .

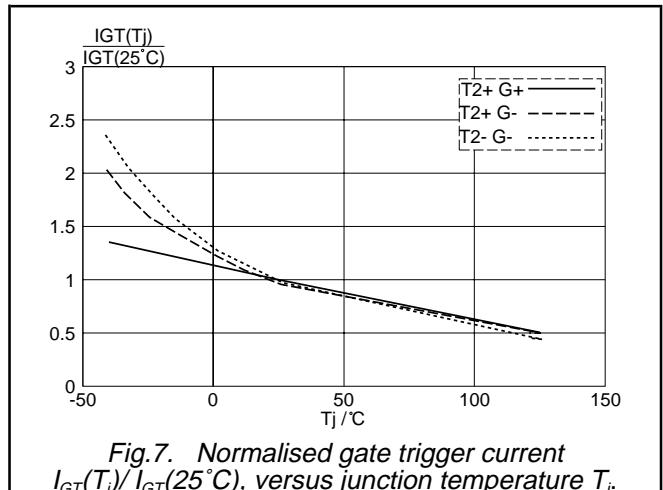


Fig.7. Normalised gate trigger current $I_{GT}(T_j)/I_{GT}(25^\circ\text{C})$, versus junction temperature T_j .

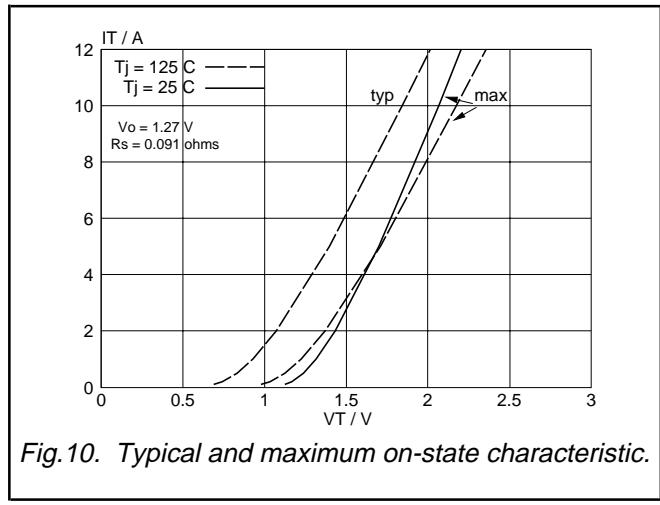


Fig.10. Typical and maximum on-state characteristic.

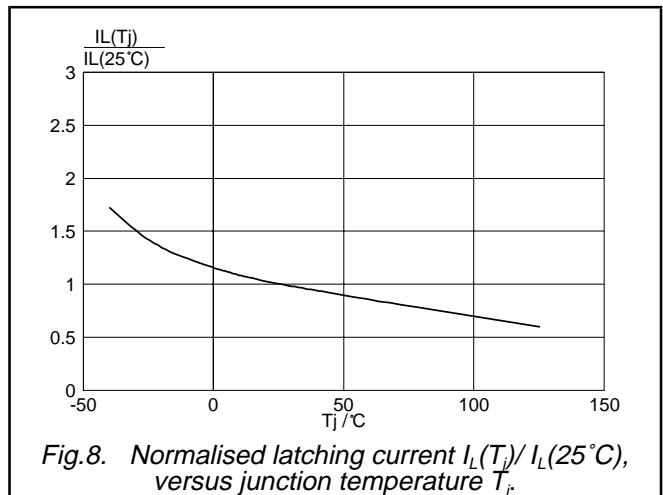


Fig.8. Normalised latching current $I_L(T_j)/I_L(25^\circ\text{C})$, versus junction temperature T_j .

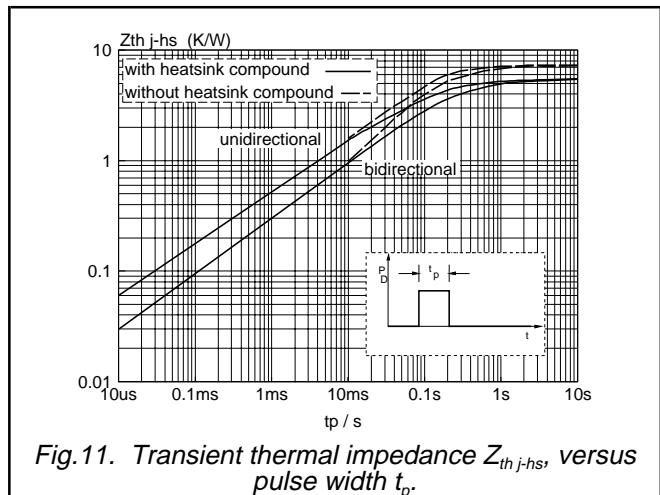


Fig.11. Transient thermal impedance $Z_{th\ j-hs}$, versus pulse width t_p .

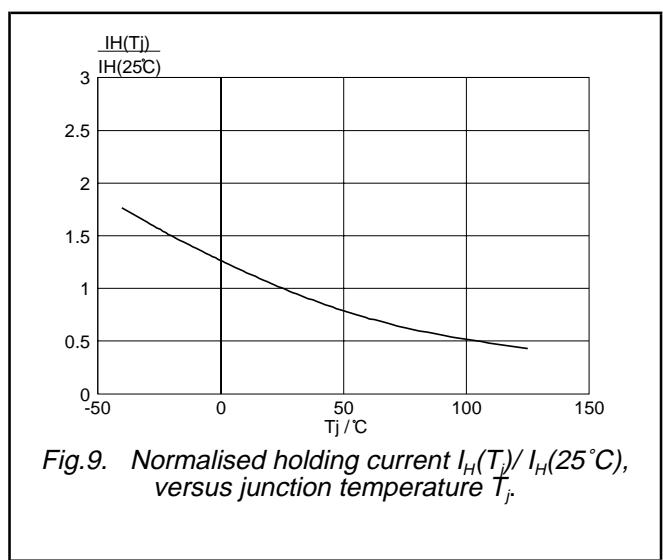


Fig.9. Normalised holding current $I_H(T_j)/I_H(25^\circ\text{C})$, versus junction temperature T_j .

MECHANICAL DATA

Dimensions in mm

Net Mass: 2 g

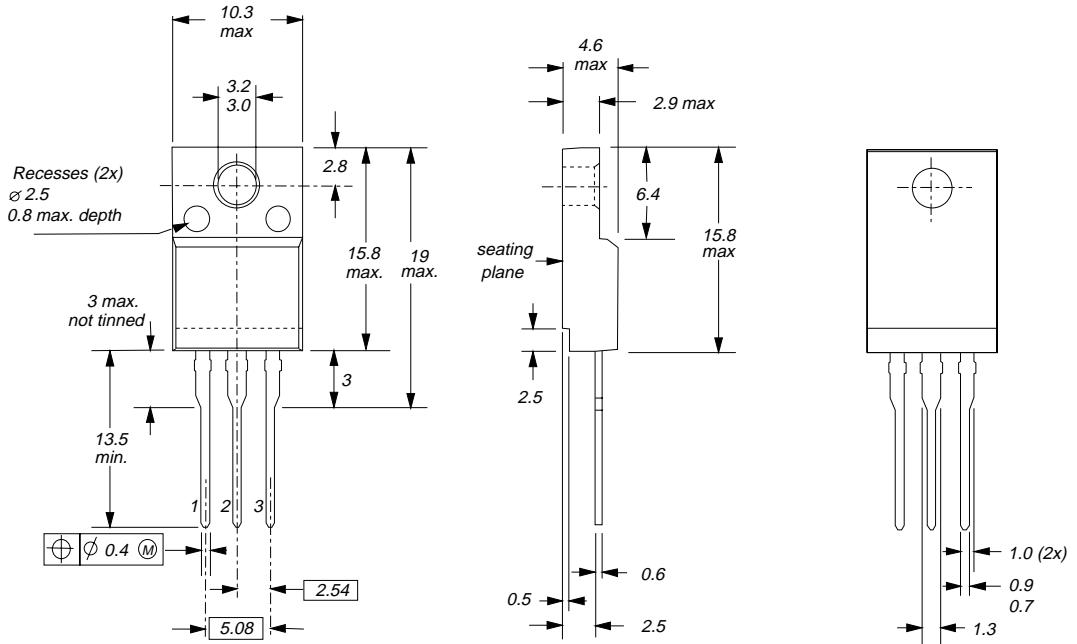


Fig.12. TO220F; The seating plane is electrically isolated from all terminals.

Notes

1. Refer to mounting instructions for F-pack envelopes.
2. Epoxy meets UL94 V0 at 1/8".